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Application No.: 10/805,933

Docket No.: JCLA10375-D

AMENDMENTSIn The Claims:**Claims 1-4 (canceled)**

5. (currently amended) A chip structure with test pads thereon, at least comprising:
a chip with an active surface having at least a flip-chip bonding pad and at least a test
pad thereon, wherein the test pad is positioned on the peripheral section of the active surface
and is electrically connected to the flip-chip bonding pad, and the chip furthermore having at
least a trace line on the active surface for connecting the test pad to the flip-chip bonding pad;
and

a passivation layer formed over the active surface, wherein the passivation layer
exposes the flip-chip bonding pad, and covers the trace line.

6. (original) The chip structure of claim 5, wherein the chip furthermore comprises at
least a fuse line buried within the chip and a fuse window having an upper surface below the
active surface of the chip for decreasing the thickness of the structure above the fuse line such
that the passivation layer fills the fuse window.

Claim 7. (canceled)

8. (original) The chip structure of claim 5, wherein the chip furthermore comprises a
bump attached to the flip-chip bonding pad.